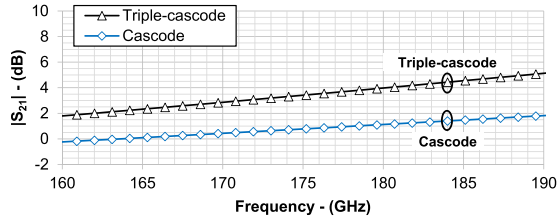


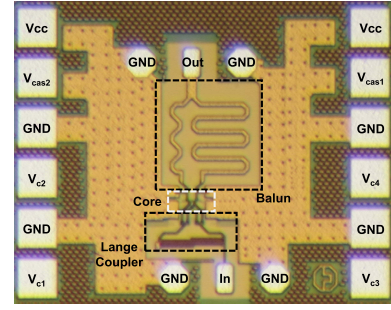
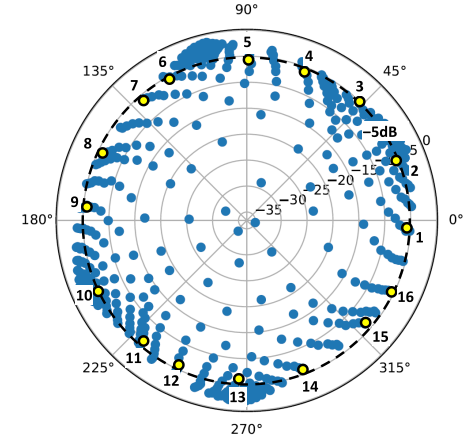
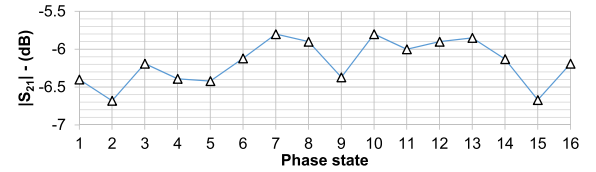
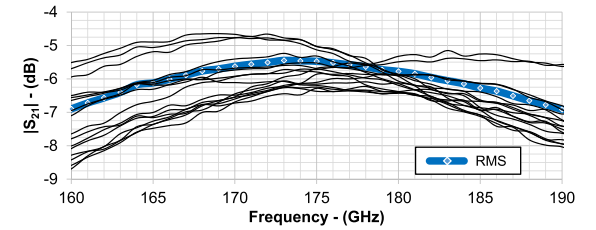
Fig. 2. Circuit schematic of the presented phase shifter.

Fig. 3. Simulated  $|S_{21}|$  of inductively peaked cascode and triple-cascode VGAs for the same operation point and design parameters used in this letter.

constant and steered between the four  $Q_1$  transistors (Fig. 1), which generate both useful quadrature and rejected-by-the-balun common-mode signals [4]. The resistors  $R_b$  of 25 k $\Omega$  isolate the input ac signals from the control voltages  $V_{c,1-4}$ , which, in turn, are decoupled by capacitors  $C_b$  (Fig. 2). The capacitance of  $C_b$  was set to 50 fF, a value obtained as the tradeoff between the gain of the VGAs, and the variations of  $|S_{11}|$ , both increasing with  $C_b$ , which is in series with the  $Q_0$  base. The triple inductively peaked cascode VGA [10] improves the small-signal gain for a given power consumption, thanks to a double-inductive peaking between the  $Q_2$  and  $Q_1$  parasitic capacitances and the inductances  $L_2$  and  $L_1$  [10], as illustrated by the simulation in Fig. 3. The inductances  $L_{1-4}$  with an average value of 15 pH in the frequency band of interest have been achieved with electrically short segments of transmission lines as in [6] and [10]. Transmission lines with characteristic impedance close to 0  $\Omega$ , referred to as *zero-ohm* lines (0  $\Omega$  in Fig. 2) [10], provide a reliable ac ground while feeding the  $Q_1$  base bias signal. The emitter area of the  $Q_{0-2}$  transistors is 4  $\mu\text{m} \times 0.9 \mu\text{m} \times 0.07 \mu\text{m}$ . Finally, the single-ended architecture in conjunction with the compact Lange coupler reduced the silicon footprint of the design.

### III. MEASUREMENT RESULTS

Fig. 4 shows the chip photographs of the phase shifter implemented in an HBT SiGe technology with a feature size of 130 nm and a maximum oscillation frequency of 450 GHz. The introduced approach allows for a core area as low as

Fig. 4. Chip photograph of the presented phase shifter. The chip dimensions are 750  $\mu\text{m} \times 570 \mu\text{m}$ .Fig. 5. Measured  $S_{21}$  polar plot at 180 GHz for a 1.8-V  $V_{CC}$ , and  $I_{CC}$  ranging from 0 to 12.5 mA in 16 steps. The best matches to 16 equidistant insertion-phase responses are annotated with yellow dots.Fig. 6. Measured at 180-GHz  $|S_{21}|$  versus the 16 states highlighted in Fig. 5.Fig. 7. Measured  $|S_{21}|$  of the 16 states highlighted in Fig. 5.

0.07 mm<sup>2</sup>. The characterization was performed on-chip with a voltage supply  $V_{CC}$  of 1.8 V, and a total collector current  $I_{CC}$  swept from 0 to 12.5 mA in 16 steps. Fig. 5 shows the measured polar diagram at 180 GHz. For an average  $I_{CC}$  of 6.9 mA, corresponding to a  $P_{dc}$  of 12.4 mW, the component provided an average IL of 6.2 dB. Fig. 6 shows the measured  $|S_{21}|$  over the 16 states highlighted in Fig. 5, and calibrated to have a resolution of 22.5°: the gain variation over the whole phase tuning range is limited to 0.9 dB. Fig. 7 illustrates the frequency response of the selected phase states. The  $|S_{21}|$  of

TABLE I  
STATE OF THE ART OF VM PHASE SHIFTERS OPERATING AT MILLIMETER-WAVE FREQUENCIES ABOVE 100 GHz

Ref.	Tech.	Area <sup>‡</sup> (mm <sup>2</sup> )	BW* (GHz)	IL (dB)	P <sub>DC</sub> <sup>a</sup> (mW)	P <sub>DC</sub> <sup>b</sup> (mW)	IL/P <sub>DC</sub> ** (1/mW)	iP <sub>1dB</sub> (dBm)	RMS Amp. Error (dB)	RMS Phase Error (degree)	S <sub>11</sub>  **,  S <sub>22</sub>  ** (dB)
[3]	130 nm SiGe	0.12	220–240	8	105	n.a.	0.004	−5 <sup>†</sup>	<1.0	n.a.	n.a.
[4]	250 nm InP	0.14	220–320	14	32	22–42	0.008	−0.7	<1.2	<12	−20, −5
[5]	50 nm GaAs	0.45	240–270	4.5	13.7	n.a.	0.042	n.a.	<1.8	<12	n.a.
[6]	130 nm SiGe	0.07	160–200	9.5	8.6	7.2–16.2	0.035	−8.4 <sup>†</sup>	<0.9	<15	−10, −10
This work	130 nm SiGe	0.07	162–190	6.2	12.4	9.9–15.3	0.041	−13.5 <sup>†</sup>	<1	<8	−10, −10

<sup>‡</sup>: core area, \*: −3 dB bandwidth from minimum IL, \*\*: worst matching, \*\*: IL in natural scale, <sup>†</sup>: simulated, <sup>a</sup>: average, <sup>b</sup>: min–max.

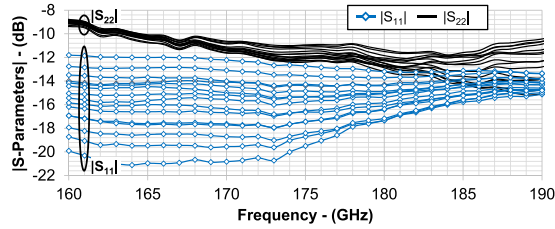


Fig. 8. Measured  $|S_{11}|$  and  $|S_{22}|$  of the 16 states highlighted in Fig. 5.

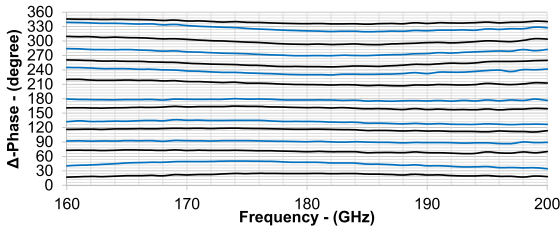


Fig. 9. Measured insertion phase-to-phase difference ( $\Delta$ -Phase) of the 16 states highlighted in Fig. 5 versus frequency.

each state is within 3 dB from the maximum value over the frequency band of 162–190 GHz, while the minimum root-mean-square (rms) IL is 5.5 dB reached at 174 GHz. The difference in the  $|S_{21}|$  frequency responses (Fig. 7) arises from different bias conditions of the VGAs, which together with asymmetries of layout, shared circuitry, and passive structures, resonate at slightly distinct frequencies. To minimize this effect, the collector bias current has been adjusted in the range between 5.5 and 8.5 mA, corresponding to a dissipated power between 9.9 and 15.3 mW. Fig. 8 presents the measured  $|S_{11}|$  and  $|S_{22}|$  of the 16 states: a matching always below −10 dB is observed. Again, the variation of the matching versus the phase states is due to different combinations of biased VGAs, which correspond to distinct impedances attached at the coupler and balun ports. Fig. 9 shows the measured insertion phase-to-phase difference response of the 16 states versus frequency. The rms amplitude and phase error versus frequency, with respect to the average response, is calculated from these measurements as in [4]. The minimum rms amplitude error is 0.3 dB, while the minimum rms phase error is 3° (Fig. 10). Fig. 11 shows the comparison of the small-signal measurements and simulations (only one state for clarity), showing agreement for the IL, while differences for input and output matching are due to the difficulties in modeling the pads. Finally, the simulated input and output power in 1-dB gain

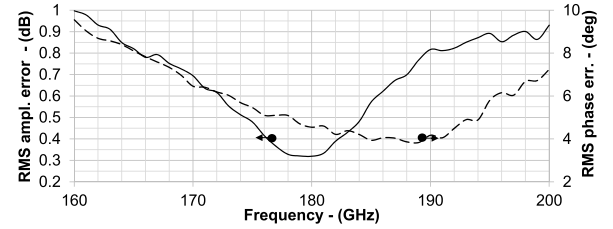


Fig. 10. Measured amplitude and phase rms errors of the 16 states highlighted in Fig. 5 versus frequency.

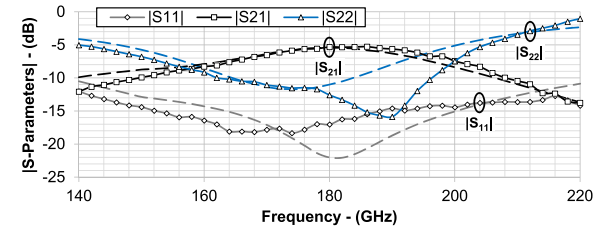


Fig. 11. Measured (solid) and simulated (dashed) S-parameters magnitude of the presented phase shifter for phase-state 7 (Fig. 5).

compression at 180 GHz for the worst linearity (state 7) are −13.5 and −20 dBm.

#### IV. CONCLUSION

A VM phase shifter for low-power and broadband applications at millimeter-wave frequencies has been presented. The component is based on a modified Gilbert-cell single-ended architecture, where the VGAs are controlled via the input transistor in place of the stacked one. Continuous 0°–360° phase control in the frequency band from 160 to 190 GHz has been demonstrated, implementing the circuit in a 130-nm SiGe BiCMOS technology. The core area of the component is 0.07 mm<sup>2</sup>, mostly set by the integrated on-chip balun and coupler used to generate quadrature and out-of-phase signals. An inductively peaked triple-cascode VGA has been used to improve the circuit efficiency in terms of small-signal gain over power consumption. Experimental results demonstrated an rms IL of 5.5 dB, with a maximum rms error of 1 dB, for an average  $P_{dc}$  of 12.4 mW. Table I gathers the obtained results and compares them against the state of the art. The presented solution achieves one of the best performances in terms of IL per power consumption together with the smallest silicon footprint.

## REFERENCES

- [1] P.-S. Wu *et al.*, “A 40–74 GHz amplitude/phase control MMIC using 90-nm CMOS technology,” in *Proc. Eur. Microw. Integr. Circuit Conf. (EuMIC)*, Munich, Germany, Oct. 2007, pp. 115–118.
- [2] M. Elkhoully, S. Glisic, F. Ellinger, and J. C. Scheytt, “120 GHz phased-array circuits in 0.25  $\mu\text{m}$  SiGe BiCMOS technology,” in *Proc. IEEE 7th German Microw. Conf. (GeMiC)*, Ilmenau, Germany, Mar. 2012, pp. 1–4.
- [3] M. Elkhoully, S. Glisic, C. Meliani, F. Ellinger, and J. C. Scheytt, “220–250-GHz phased-array circuits in 0.13  $\mu\text{m}$  SiGe BiCMOS technology,” *IEEE Trans. Microw. Theory Techn.*, vol. 61, no. 8, pp. 3115–3127, Aug. 2013.
- [4] Y. Kim, S. Kim, I. Lee, M. Urteaga, and S. Jeon, “A 220–320-GHz vector-sum phase shifter using single Gilbert-cell structure with lossy output matching,” *IEEE Trans. Microw. Theory Techn.*, vol. 63, no. 1, pp. 256–265, Jan. 2015.
- [5] D. Müller, A. Tessmann, A. Leuther, T. Zwick, and I. Kallfass, “A H-band vector modulator MMIC for phase-shifting applications,” in *IEEE MTT-S Int. Microw. Symp. Dig.*, Phoenix, AZ, USA, May 2015, pp. 1–4.
- [6] P. V. Testa, C. Carta, and F. Ellinger, “A 140–210 GHz low-power vector-modulator phase shifter in 130 nm SiGe BiCMOS technology,” in *Proc. IEEE APMC*, Kyoto, Japan, Nov. 2018, pp. 530–532.
- [7] K.-J. Koh and G. M. Rebeiz, “0.13- $\mu\text{m}$  CMOS phase shifters for X-, Ku-, and K-band phased arrays,” *IEEE J. Solid-State Circuits*, vol. 42, no. 11, pp. 2535–2546, Nov. 2007.
- [8] F. Akbar and A. Mortazawi, “A frequency tunable 360° analog CMOS phase shifter with an adjustable amplitude,” *IEEE Trans. Circuits Syst. II: Exp. Briefs*, vol. 64, no. 12, pp. 1427–1431, Dec. 2017.
- [9] D. Shin, C.-Y. Kim, D.-W. Kang, and G. M. Rebeiz, “A high-power packaged four-element X-band phased-array transmitter in 0.13- $\mu\text{m}$  CMOS for radar and communication systems,” *IEEE J. Solid-State Circuits*, vol. 61, no. 8, pp. 3060–3071, Aug. 2013.
- [10] P. V. Testa, C. Carta, and F. Ellinger, “Analysis and design of a 200-GHz SiGe-BiCMOS loss-compensated distributed power divider,” *IEEE Trans. Microw. Theory Techn.*, vol. 66, no. 9, pp. 3927–3936, Sep. 2018.
- [11] P. V. Testa, C. Carta, B. Klein, R. Hahnel, D. Plettemeier, and F. Ellinger, “A 210-GHz SiGe balanced amplifier for ultrawideband and low-voltage applications,” *IEEE Microw. Wireless Compon. Lett.*, vol. 27, no. 3, pp. 287–289, Mar. 2017.